

#### 500 Volt, 3.0Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

#### Product Summary

| Part Number  | BV <sub>DSS</sub> | R <sub>Ds(on)</sub> | I <sub>D</sub> |
|--------------|-------------------|---------------------|----------------|
| JANTX2N6794  | 500V              | 3.0Ω                | 1.5A           |
| JANTXV2N6794 |                   |                     |                |

#### Features:

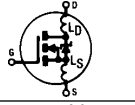
- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

#### Absolute Maximum Ratings

|  | Parameter                   | JANTX2N6794, JANTXV2N6794                          | Units |
|--|-----------------------------|--|-------|
| I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C  | Continuous Drain Current    | 1.5  | A     |
| I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C | Continuous Drain Current    | 1.0  |       |
| I <sub>DM</sub>  | Pulsed Drain Current ①      | 6.0  |       |
| P <sub>D</sub> @ T <sub>C</sub> = 25°C                         | Max. Power Dissipation      | 20   | W     |
|  | Linear Derating Factor      | 0.16   | W/K ⑤ |
| V <sub>GS</sub>  | Gate-to-Source Voltage      | ±20  | V     |
| dv/dt  | Peak Diode Recovery dv/dt ③ | 3.5  | V/ns  |
| T <sub>J</sub>   | Operating Junction          | -55 to 150   | °C    |
| T <sub>STG</sub>   | Storage Temperature Range   |  |       |
|  | Lead Temperature            | 300 (0.063 in. (1.6mm) from case for 10.5 seconds) |       |
|  | Weight                      | 0.98 (typical)                                     | g     |

# JANTX2N6794, JANTXV2N6794 Device

## Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)

|                                     | Parameter                                    | Min. | Typ. | Max. | Units  | Test Conditions  |
|-------------------------------------|--|------|------|------|--------|--|
| BV <sub>DSS</sub>                   | Drain-to-Source Breakdown Voltage            | 500  | —    | —    | V      | V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.0 mA  |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Temperature Coefficient of Breakdown Voltage | —    | 0.43 | —    | V/°C   | Reference to 25°C, I <sub>D</sub> = 1.0 mA   |
| RDS(on)                             | Static Drain-to-Source                       | —    | —    | 3.0  | Ω      | V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.0A ④   |
|                                     | On-State Resistance                          | —    | —    | 3.45 |        |  |
| VGS(th)                             | Gate Threshold Voltage                       | 2.0  | —    | 4.0  | V      | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA   |
| g <sub>fs</sub>                     | Forward Transconductance                     | 1.0  | —    | —    | S (r̄) | V <sub>DS</sub> > 15V, I <sub>DS</sub> = 1.0A ④  |
| IDSS                                | Zero Gate Voltage Drain Current              | —    | —    | 25   | μA     | V <sub>DS</sub> = 0.8 x Max Rating, V <sub>GS</sub> = 0V   |
|                                     |  | —    | —    | 250  |        |  |
| IGSS                                | Gate-to-Source Leakage Forward               | —    | —    | 100  | nA     | V <sub>GS</sub> = 20V  |
| IGSS                                | Gate-to-Source Leakage Reverse               | —    | —    | -100 | nA     | V <sub>GS</sub> = -20V   |
| Q <sub>g</sub>                      | Total Gate Charge                            | 7.3  | —    | 16.7 | nC     | V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.5A<br>V <sub>DS</sub> = Max. Rating x 0.5<br>see figures 6 and 13  |
| Q <sub>gs</sub>                     | Gate-to-Source Charge                        | 0.1  | —    | 3.0  |        |  |
| Q <sub>gd</sub>                     | Gate-to-Drain ("Miller") Charge              | 3.7  | —    | 8.7  |        |  |
| t <sub>d(on)</sub>                  | Turn-On Delay Time                           | —    | —    | 40   | ns     | V <sub>DD</sub> = 250V, I <sub>D</sub> = 1.5A,<br>R <sub>G</sub> = 7.5Ω, V <sub>GS</sub> = 10V<br><br>see figure 10  |
| t <sub>r</sub>                      | Rise Time                                    | —    | —    | 30   |        |  |
| t <sub>d(off)</sub>                 | Turn-Off Delay Time                          | —    | —    | 60   |        |  |
| t <sub>f</sub>                      | Fall Time                                    | —    | —    | 30   |        |  |
| LD                                  | Internal Drain Inductance                    | —    | 5.0  | —    | nH     | <p>Measured from the drain lead, 6mm (0.25 in.) from package to center of die.</p> <p>Modified MOSFET symbol showing the internal inductances.</p>  |
| LS                                  | Internal Source Inductance                   | —    | 15   | —    |        |  |
| C <sub>iss</sub>                    | Input Capacitance                            | —    | 350  | —    | pF     | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V<br>f = 1.0 MHz<br>see figure 5   |
| C <sub>oss</sub>                    | Output Capacitance                           | —    | 80   | —    |        |  |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                 | —    | 35   | —    |        |  |

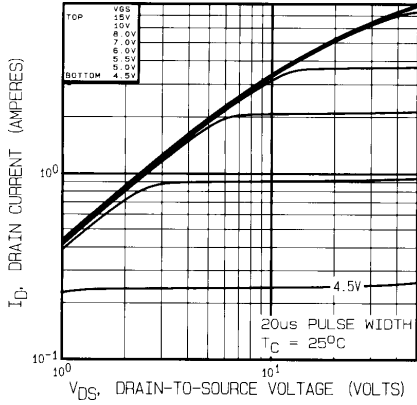
## Source-Drain Diode Ratings and Characteristics

|                 | Parameter                              | Min.   | Typ. | Max. | Units | Test Conditions   |
|-----------------|--|--|------|------|-------|---|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —  | —    | 1.5  | A     | Modified MOSFET symbol showing the integral reverse p-n junction rectifier. |
| I <sub>SM</sub> | Pulse Source Current (Body Diode) ①    | —  | —    | 6.0  |       |   |
| V <sub>SD</sub> | Diode Forward Voltage                  | —  | —    | 1.2  | V     | T <sub>j</sub> = 25°C, I <sub>S</sub> = 1.5A, V <sub>GS</sub> = 0V ④        |
| t <sub>rr</sub> | Reverse Recovery Time                  | —  | —    | 900  | ns    | T <sub>j</sub> = 25°C, I <sub>F</sub> = 1.5A, di/dt ≤ 100A/μs               |
| Q <sub>RR</sub> | Reverse Recovery Charge                | —  | —    | 5.9  | μC    | V <sub>DD</sub> ≤ 50V ④   |
| t <sub>on</sub> | Forward Turn-On Time                   | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> . |      |      |       |   |

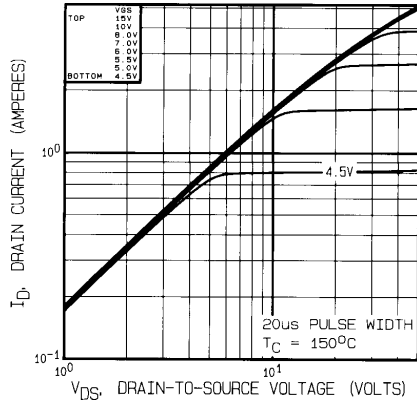
## Thermal Resistance

|                   | Parameter           | Min. | Typ. | Max. | Units | Test Conditions      |
|-------------------|---------------------|------|------|------|-------|----------------------|
| R <sub>thJC</sub> | Junction-to-Case    | —    | —    | 6.25 | K/W   | Typical socket mount |
| R <sub>thJA</sub> | Junction-to-Ambient | —    | —    | 175  |       |                      |

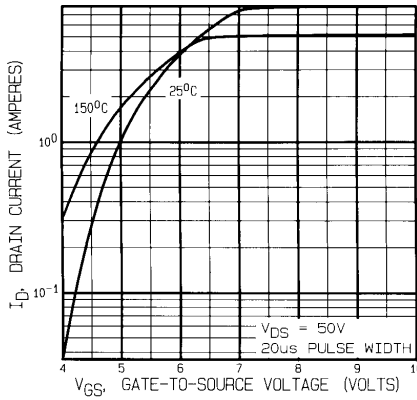
# JANTX2N6794, JANTXV2N6794 Device



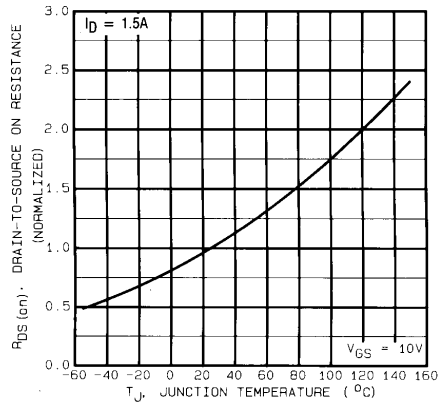
**Fig. 1 — Typical Output Characteristics**  
 $T_C = 25^\circ\text{C}$



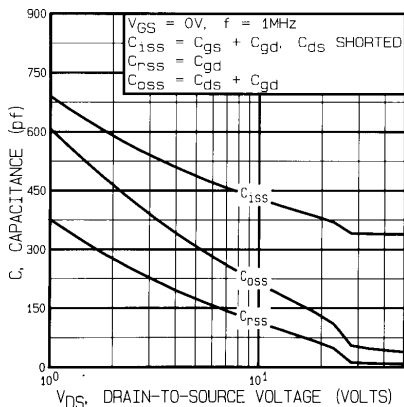
**Fig. 2 — Typical Output Characteristics**  
 $T_C = 150^\circ\text{C}$



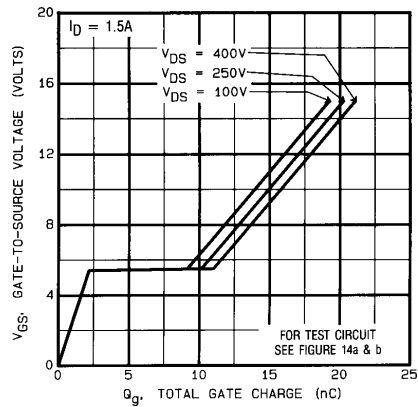
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**

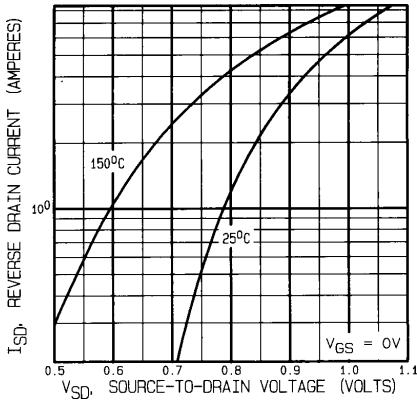


**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**

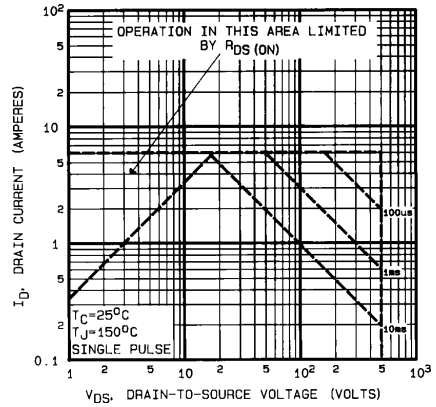


**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

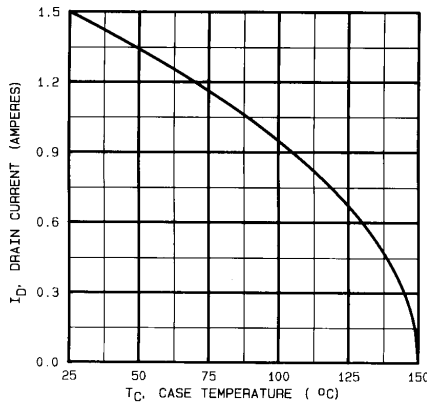
# JANTX2N6794, JANTXV2N6794 Device



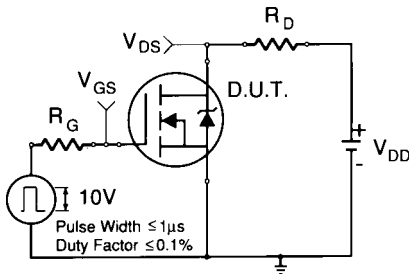
**Fig. 7 — Typical Source-to-Drain Diode Forward Voltage**



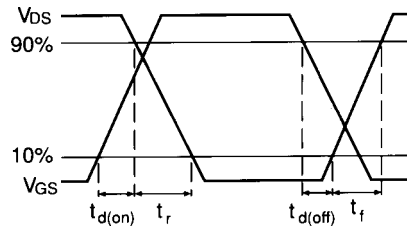
**Fig. 8 — Maximum Safe Operating Area**



**Fig. 9 — Maximum Drain Current Vs. Case Temperature**



**Fig. 10a — Switching Time Test Circuit**



**Fig. 10b — Switching Time Waveforms**

# JANTX2N6794, JANTXV2N6794 Device

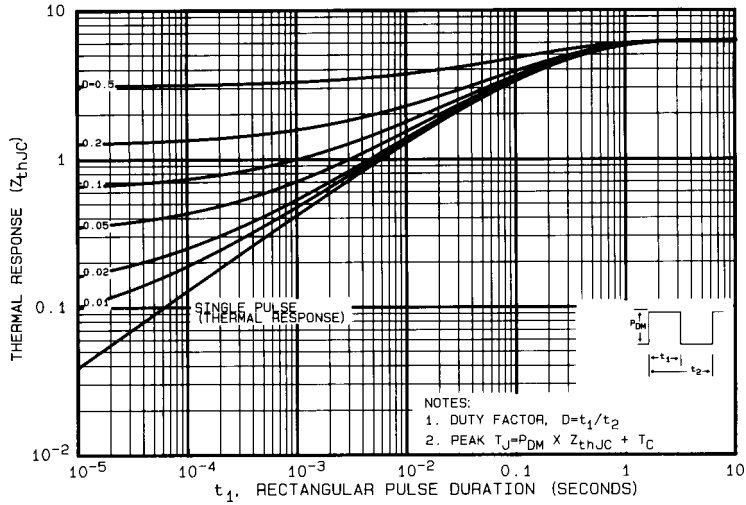


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

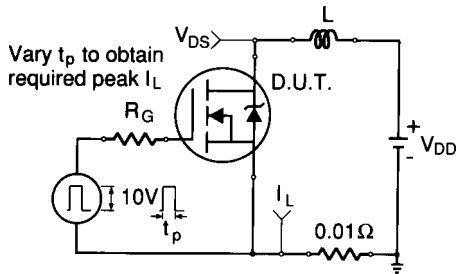


Fig. 12a — Unclamped Inductive Test Circuit

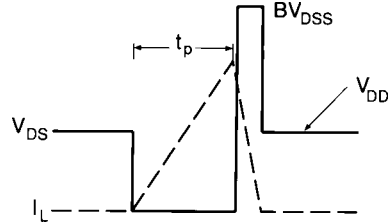


Fig. 12b — Unclamped Inductive Waveforms

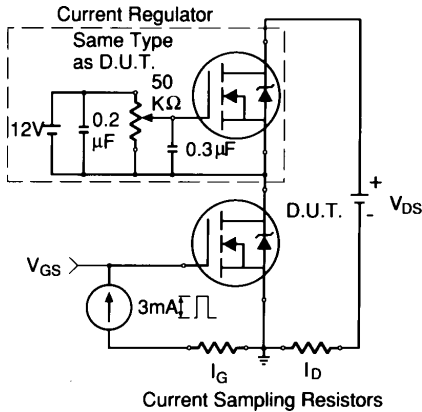


Fig. 13a — Gate Charge Test Circuit

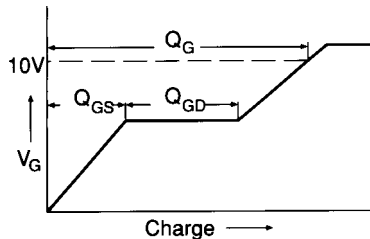
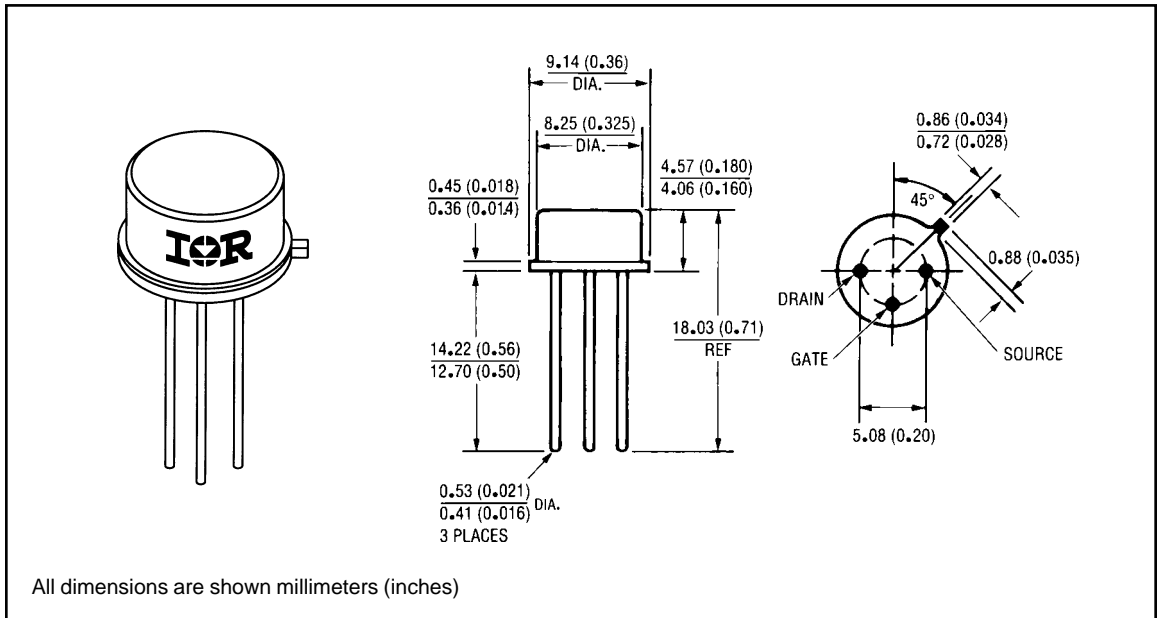


Fig. 13b — Basic Gate Charge Waveform

# JANTX2N6794, JANTXV2N6794 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature. (see figure 11)
- ② @  $V_{DD} = 50V$ , Starting  $T_J = 25^\circ C$ ,  
 $EAS = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$   
 Peak  $I_L = 1.5A$ ,  $V_{GS} = 10V$ ,  $25 \leq R_G \leq 200\Omega$
- ③  $I_{SD} \leq 1.5A$ ,  $di/dt \leq 50A/\mu s$ ,  
 $V_{DD} \leq BV_{DSS}$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤  $K/W = ^\circ C/W$   
 $W/K = W/^\circ C$

## Case Outline and Dimensions — TO-205AF (Modified TO-39)



International  
**IR** Rectifier

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